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INFORMATION DISCLOSURE STATEMENT BY APPLICANT

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1

of

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Complete If Known	
Application Number	10/660,048
Filing Date	September 11, 2003
First Named Inventor	Lanzerotti, et al.
Group Art Unit	2826
Examiner Name	Quach, Tuan N.

Attorney Docket Number

BUR920010146US2

U.S. PATENT DOCUMENTS

Examiner Initials*	Cite No. ¹	U.S. Patent Document Number	Kind Code ² (if known)	Name of Patentee or Applicant/Inventor of Cited Document	Date of Publication of Cited Document MM-DD-YYYY	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
TQ		5,734,183		Morishita	03/31/1998	
TQ		6,246,104 B1		Tsuda, et al.	06/12/2001	

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Examiner Initials*	Cite No. ¹	Office ³	Foreign Patent Number	Kind Code ⁵ (if known)	Name of Patentee or Applicant/Inventor of Cited Document	Date of Publication of Cited Document MM-DD-YYYY	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T ⁶

OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published	T ²

Examiner Signature

/Tuan Quach/

Date Considered

08/19/06

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¹ Unique citation designation number. ² See attached Kinds of U.S. Patent Documents. ³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). ⁴ For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵ Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST.16 if possible. ⁶ Applicant is to place a check mark here if English language Translation is attached.

INFORMATION DISCLOSURE CITATION (Use several sheets if necessary)				ATTY DOCKET NO. BUR920010146US2		SERIAL NO. 10/660,048 Not Yet Assigned	
				Lanzerotti et al.			
				FILING Concurrently Herewith		GROUP Unknown	
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		5,116,455	05/26/1992	Daly	_____	_____	
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TQ		JP11312685A	11/09/1999	Japan w/Abstract	_____	_____	✓
		JP2000012558A	01/14/2000	Japan w/Abstract	_____	_____	✓
		JP92000174033A	06/23/2000	Japan w/Abstract	_____	_____	✓
TQ		WO 98/26457	06/18/1998	Germany	_____	_____	✓
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TQ			Lanzerotti et al., "Suppression of Boron Outdiffusion in SiGe HBTs by Carbon Incorporation", 1996 IEEE, pp. 10.2.1 - 10.2.4				
TQ			Stock et al. "Carbon Incorporation in Silicon for Suppressing Interstitial-Enhanced Boron Diffusion", Applied Physics Letter, March 13, 1995, Vol. 66, Issue 11, pp. 1370-1372				
EXAMINER /Tuan Quach/				DATE CONSIDERED 08/21/2006			
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	Lanzerotti et al.	
	FILING Concurrently Herewith	GROUP Unknown

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						YES	NO

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TQ		Ghanti et al., "Control of Implant-Damage-Enhanced Boron Diffusion in Epitaxially Grown Si/p-Siz-x Ge/n-Si Heterojunction Bipolar Transistors", Journal of Electronic Materials, Vol. 24, No. 8, 1995, pp. 999-1002
TQ		Bodnar et al., "Growth of Ternary Alloy Siz-x-yGeCy By Rapid Thermal Chemical Vapor Deposition", Journal Vac. Science Technology, A., Vol. 1. 13, N. 5, Sept/Oct. 1995, pp.2336-2340

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